







### **Product Outline:**

This is the high efficiency LED with reflector type. EMC 3030 Single color is a surfacemount LED which with heat sink to enhance operating performance. With special binning technology, these LEDs are ideal for architecture lighting and special lighting needs.

# Features:

- Red color
- High brightness output @ 150mA,
- High driving current to 200mA.
- Package Dimension = 3.2mmX3.0mmX0.6mm
- RoHS compliant
- Custom Bin available upon special request

# **Application:**

- Warning lamp
- Decoration lamp
- Architecture Lighting
- Garden Lighting
- Horticulture Lighting

### **Compliance and Certification:**

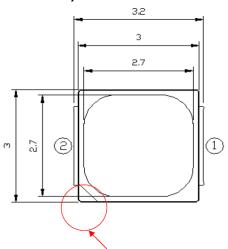


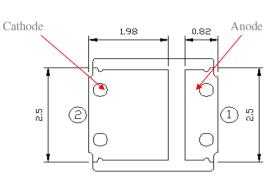




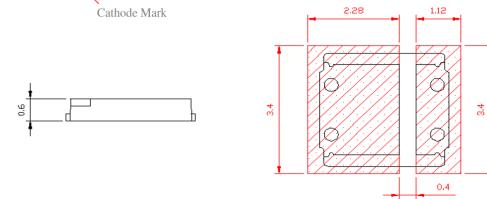
# **Mechanical Property:**







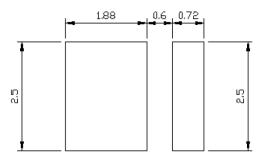
Recommended Solder Pad Design



\* All dimensions are in millimeters,

\* Tolerances are ± 0.10mm.

### **Recommended Solder footprint:**



\* All dimensions are in millimeters.

- \* The LEDs is designed to be reflow soldered on to a PCB. IF dip soldered that QL cannot guarantee its reliability.
- \* Reflow soldering must not be performed more than twice.





# Characteristics

Absolute Maximu	(Ta=25℃)		
Parameter	Symbol	Rating	Unit
DC Forward Current	lf	200	mA
Leakage Current	lr	1.0	μA
Power Dissipation	Pd	0.6	w
Pulse Forward Current	lfp	240	mA
LED Junction Temperature	TJ	125	°C
Storage Temperature	Tstg	-40 ~ 100	°C
Operation Temperature	Topr	-40 ~ 85	°C
Soldering Temperature	Tsol	260 < 10 sec	°C
ESD Sensitivity(HBM)		8	KV
Thermal Resistance	Rth	10	°CW

(1) Proper current rating must be observed to maintain junction temperature below maximum at all time (2) IFP Condition: Duty 1/10, Pulse within 10msec

# Electrical / Optical Characteristic

(Ta=25 oC)

Product	Color	I <sub>F</sub> (mA)	V <sub>F</sub> (V)		Wavelength		htness n/mW)
			Typ. max	nm	min	typ.	
QLSP04RH	Red	150	2.2	2.6	615~630	18 lm	23 lm





Groups Dominant Wavelength

Wd (nm) @ 150mA				
Color	Code name	Min.	Max.	
	A7	615	620	
Red	A8	620	625	
	A9	625	630	

Measurement tolerance is +/- 1nm

#### Forward Voltage (V<sub>F</sub>) Bin:

VF Rank @ 150mA (Vf)				
Color	Code name	Low	High	
	PQ	1.8	2.0	
Red	RS	2.0	2.2	
	TU	2.2	2.4	

The forward voltage tolerance is  $\pm \ 0.1 V$ 

#### Luminous Flux Bin:

Rank @ 150mA (Im)				
Color	Code name	Low	High	
Pod	QIJ	18	22.5	
Red	QKM	22.5	31.5	

luminous flux tolerance is ± 7%

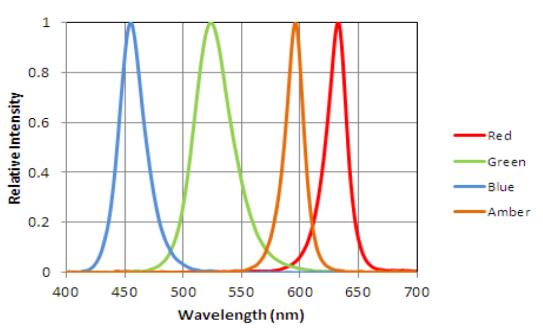




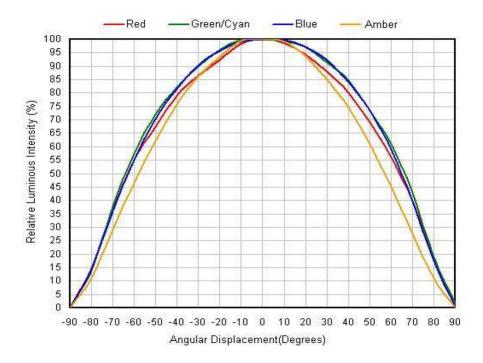
QLSP04RH V1.0

**Characteristic Curves** 





#### (2). Typical Representative Spatial Radiation Pattern

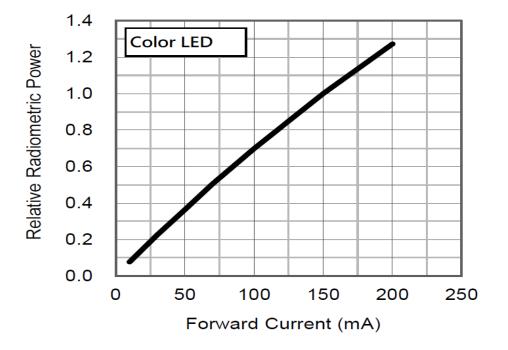




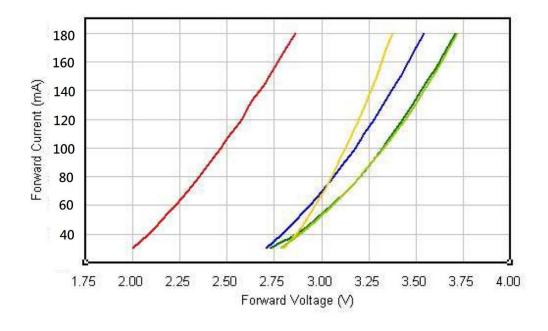




#### (3). Forward Current Characteristics



(4). Forward Current vs Forward Voltage





# Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	$25^{\circ}$ C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40 $^\circ\!\!\mathbb{C}$	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature $60^\circ\!\mathrm{C}$	60℃ Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature $85^\circ\!\!\mathbb{C}$	85℃ Operating	1000 Hrs	20 pcs
5	Low temperature storage -40 $^\circ \! \mathbb{C}$	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100 $^\circ\!\mathrm{C}$	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat $60^\circ\!\!\!\!\!C90\%$	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	$25^{\circ}$ C10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60℃, 60%RH for 52hrs Tsld max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25℃~65℃~-10℃, 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40℃/ 20minr~ 5minr~100℃ /20min	300 Cycle	20 pcs

# Judgment Criteria:

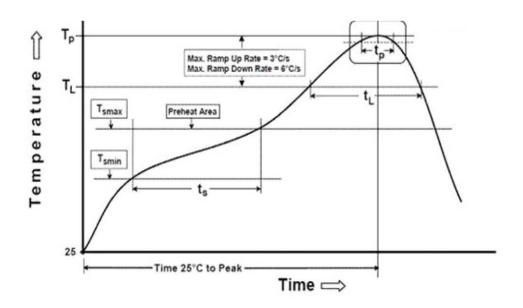
Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	150 mA	∆Vf< 10%
Luminous Flux	lv	150 mA	<b>∆Iv&lt; 30%</b>





### **Solder Profile:**

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

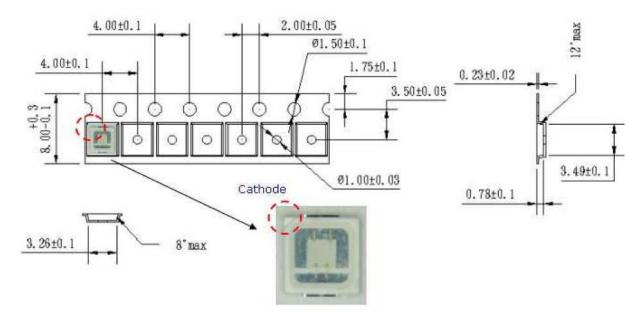


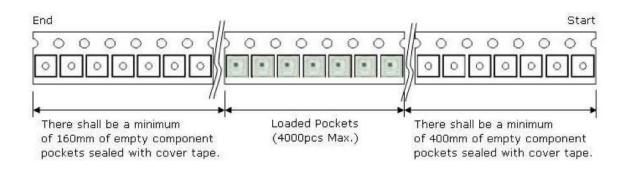
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Temperature Min(T <sub>smin</sub> )	100℃	150℃
Temperature Max(T <sub>smax</sub> )	150°C	<b>200</b> ℃
Time(t <sub>a</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up rate( $T_L$ to $T_P$ )	3℃/second max.	3℃/second max.
Liquidous Temperature(T <sub>L</sub> )	183℃	<b>217</b> ℃
Time( $t_L$ ) maintained above $T_L$	60-150 seconds	60-150 seconds
Peak package body temperature(T <sub>P</sub> )	235℃	260℃
Time within 5° $_{\mathbb C}$ of Actual Peak	202222742*	20 accorda*
temperature (t <sub>p</sub> )	20seconds*	30 seconds*
Ramp-down rate( $T_P$ to $T_L$ )	6℃/second max.	6℃/second max.
Time 25℃ to peak temperature	6 minutes max.	8 minutes max.

 $^*$  Tolerance for peak profile temperature (T\_P) is defined as a supplier minimum and a user maximum.



# Taping & Packing:

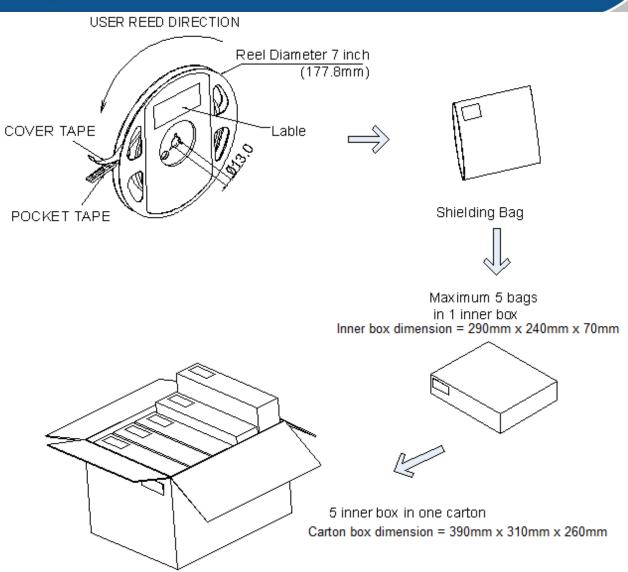




Unit : mm











# Labeling

Quantity: XX	<b>   </b>        <b> </b>	l	QueLighting
	P/N: XXXXXX		

# Ordering Information:

Part #	Multiple Quantities	Quantity per Reel
QLSP04RH		1000, 2000 pcs

# **Revision History:**

Revision Date:	Changes:	Version #:
09-21-2020	Initial release	1.0

